

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
200V	120mΩ@10V	18A

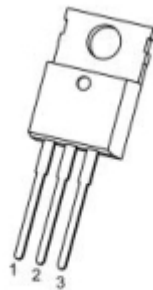
Feature

- Fast Switching
- Low Gate Charge and Rdson
- 100% Single Pulse avalanche energy Test

Applications

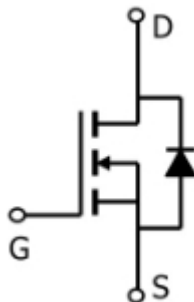
- DC-DC Converter
- Ideal for high-frequency switching and synchronous rectification

Package

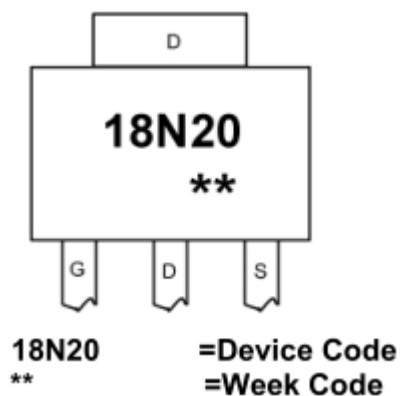


TO-220-3L-C(G:1 D:2 S:3)

Circuit diagram



Marking



Absolute maximum ratings

(T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	200	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current ¹ (TC=25°C)	I _D	18	W
Pulsed Drain Current	I _{DM}	72	A
Single Pulse Avalanche Energy ³	E _{AS}	247	mJ
Total Power Dissipation(TC=25°C)	P _D	150	W
Thermal Resistance Junction- Case ¹	R _{θJC}	0.83	°C/ W
Storage Temperature Range	T _{STG}	-55~ +150	°C
Operating Junction Temperature Range	T _J	-55~ +150	°C

Electrical characteristics

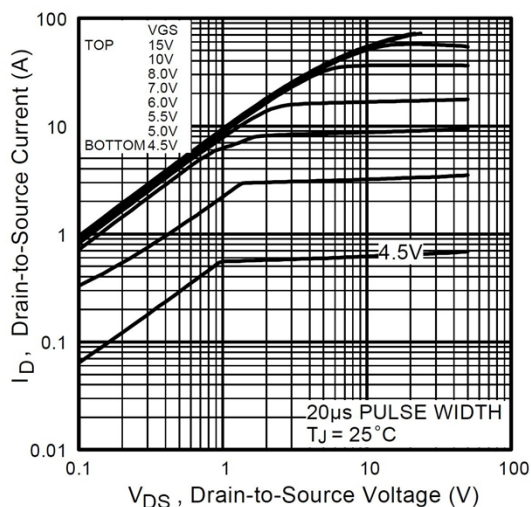
($T_A=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} = 0V, I _D =250μA	200			V
Bvdss Temperature Coefficient	Δ BVDSS/ΔTJ	I _D =1mA,Reference25 °C		0.25		V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =160V,V _{GS} = 0V , T _J =25°C			25	uA
Gate-body leakage current	I _{GSS}	V _{GS} = ±30V , V _{DS} =0V			±100	uA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =16A		120	150	Ω
Dynamic characteristics ⁴						
Input Capacitance	C _{iSS}	V _{DS} =25V, V _{GS} =0V, f=1MHz		1220		pF
Output Capacitance	C _{oSS}			270		
Reverse Transfer Capacitance	C _{rSS}			66		
Switching Characteristics						
Total Gate Charge(4.5V)	Q _g	V _{DS} =100V, V _{GS} =10V, I _D =16A		67		nC
Gate-Source Charge	Q _{gS}			17		
Gate-Drain Charge	Q _{gd}			29		
Turn-On Delay Time	T _{d(on)}	V _{DD} =250V, V _{GS} =10V, R _G =10Ω, I _D =14A		28		nS
Rise Time	T _r			47		
Turn-Off Delay Time	T _{d(off)}			57		
Fall Time	T _f			40		

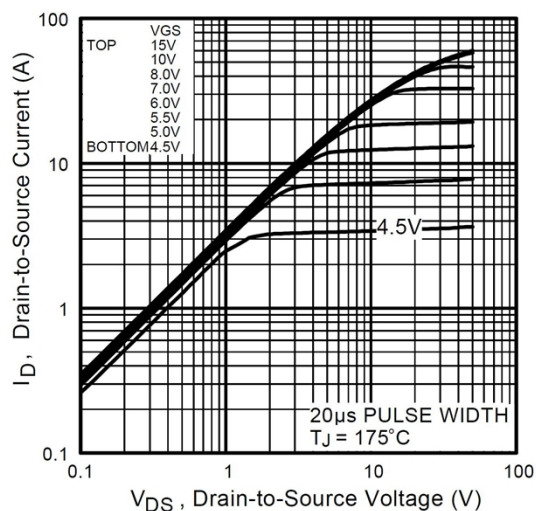
Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is $R_G = 25\Omega, L = 10mH$

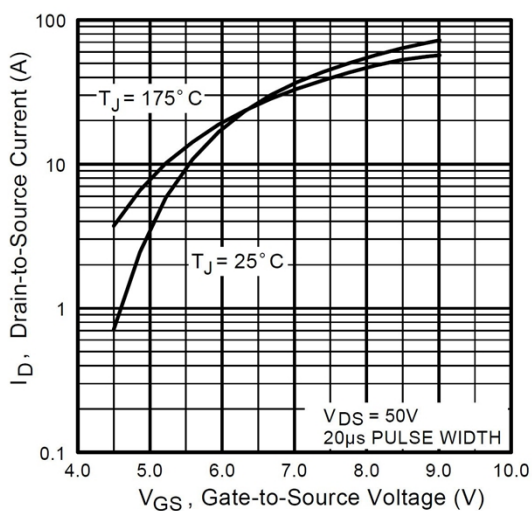
Typical Characteristics



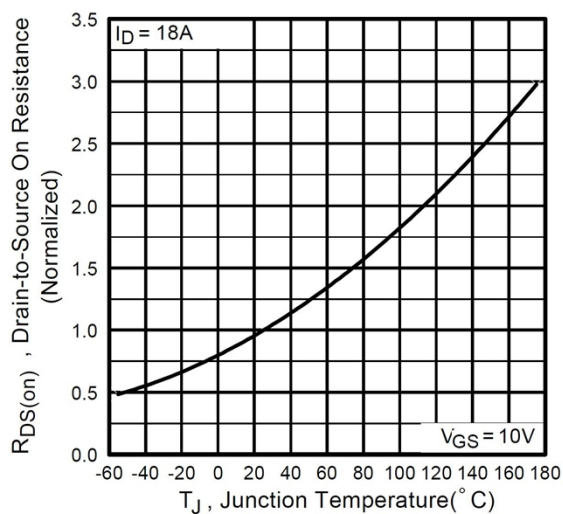
Typical Output Characteristics



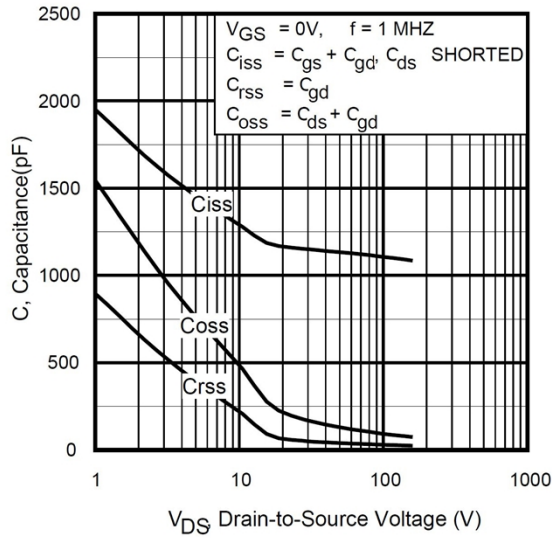
Typical Output Characteristics



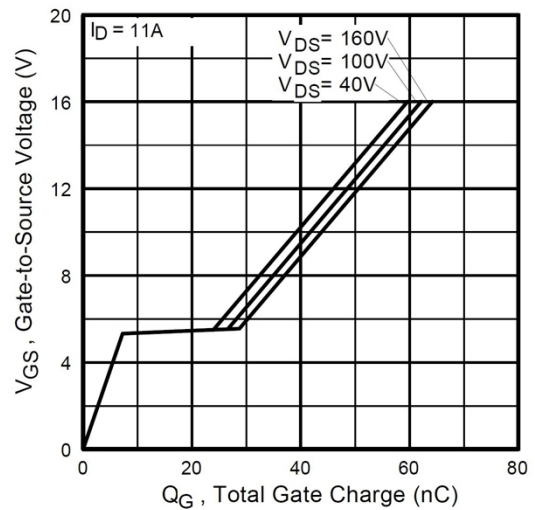
Typical Transfer Characteristics



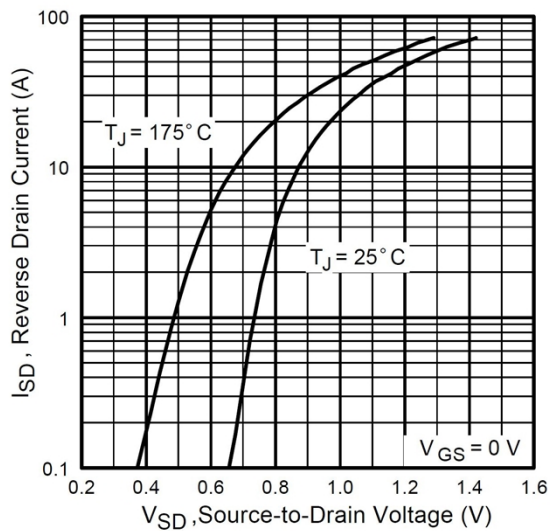
Normalized On-Resistance Vs. Temperature



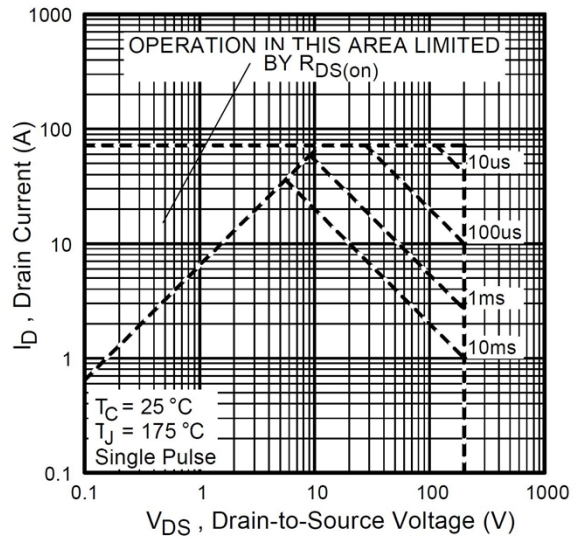
Typical Capacitance Vs. Drain-to-Source Voltage



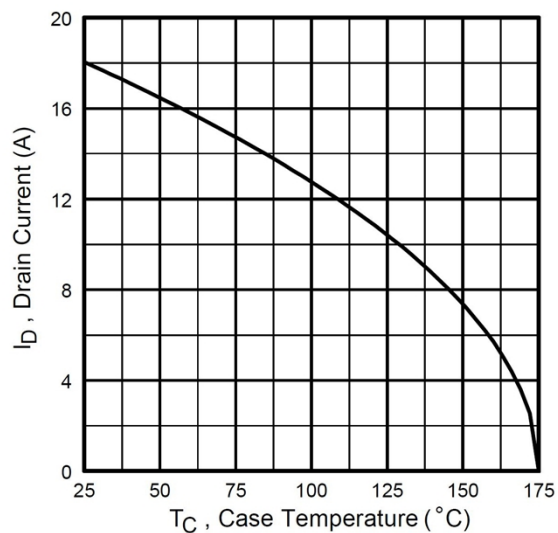
Typical Gate Charge VS. Gate-to-Source Voltage



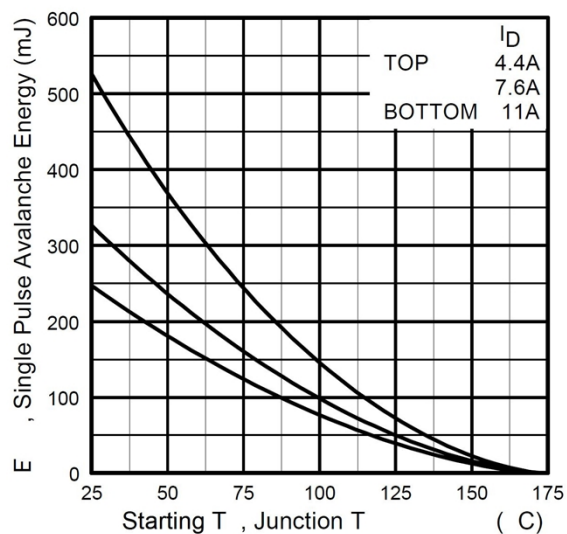
Typical Source-Drain Diode Forward Voltage



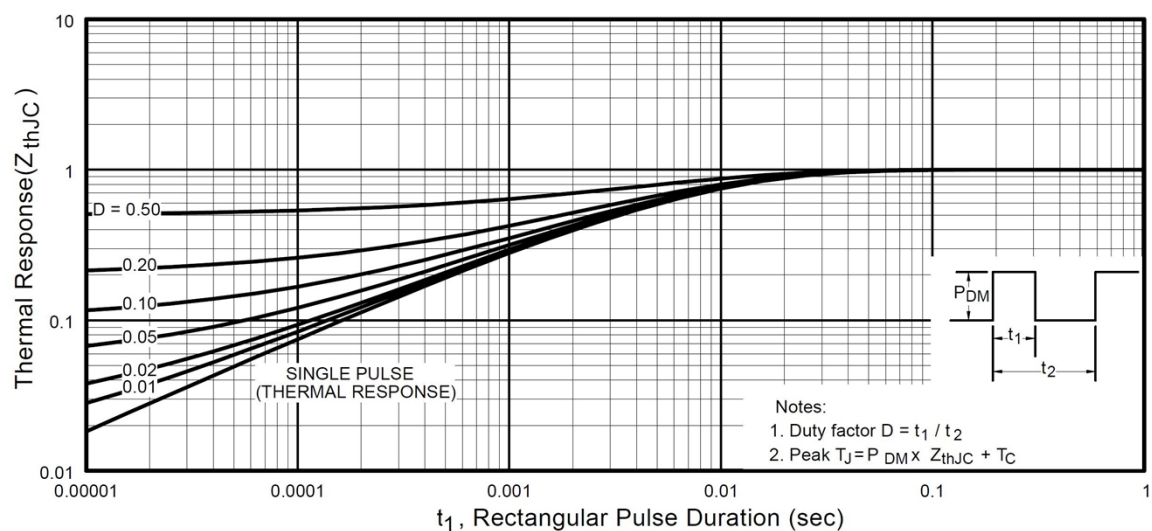
Maximum Safe Operating Area



Maximum Drain Current Vs. Case Temperature

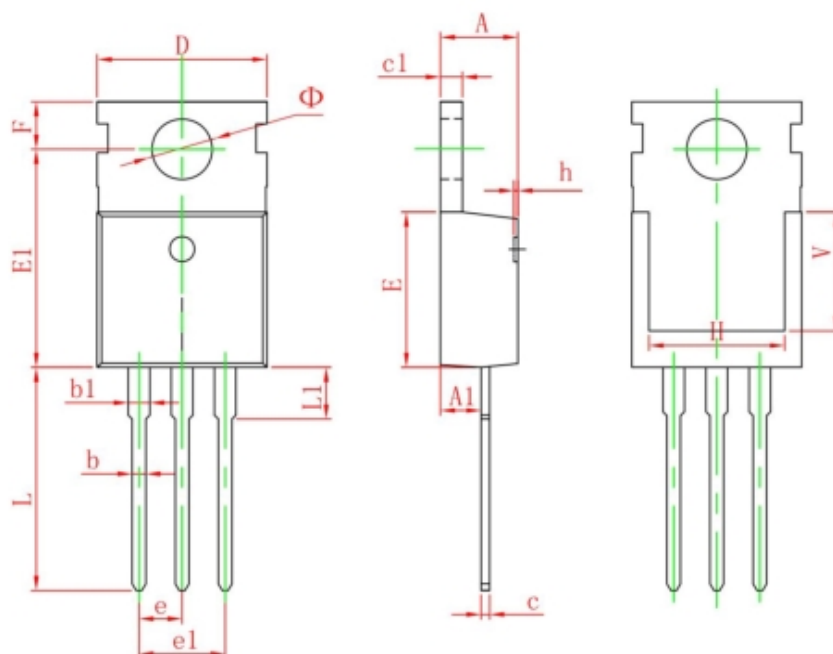


Maximum Avalanche Energy Vs. Drain Current



Maximum Effective Transient Thermal Impedance, Junction-to-Case

TO-220-3L-C Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.950	9.750	0.352	0.384
E1	12.650	13.050	0.498	0.514
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	6.900 REF.		0.276 REF.	
Φ	3.400	3.800	0.134	0.150